Heraeus

Technical Data Sheet



THICK FILM MATERIALS

Product Type: Conductors

Product Name: C2129A



Pb and Cd Free Silver/Palladium Conductor

Description

C2129A is a high performance Pb, Cd and Ni free mixed bonded Ag/Pd conductor material. It offers cost savings over standard Ag/Pd formulations while maintaining the advantages of leach resistance and aged adhesion. C2129A is also aluminum wire bondable.

C2129A is supplied with a rheology, which results in a dense, uniform fired film.

Key Benefits

- Low cost
- Excellent solderability and leach resistance
- Low resistivity
- Pb, Cd and Ni free
- Good Al wire bond adhesion (initial and aged)

Recommended Processing Guidelines

Printing

280 – 325 mesh stainless steel screen 0.5 mil emulsion 1.1 mil wire

Coverage

 $85 \text{ cm}^2/\text{g}$ at $12 \mu m$ fired film thickness

Drying

150 °C for 10 minutes

Firing

850 °C peak temperature

Dwell time at peak temperature for 10 minutes

Film Thickness:

 $\begin{array}{lll} \text{Wet:} & 30-36 \ \mu\text{m} \\ \text{Dried:} & 22-27 \ \mu\text{m} \\ \text{Fired:} & 10-15 \ \mu\text{m} \end{array}$

Thinner:

RV-372

Warranty:

Material guaranteed to meet specifications for 6 months from date of shipment.

Storage:

Store in a dry location at 5 - 25 °C.

DO NOT REFRIGERATE.

Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.



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Typical Properties

Resistivity

 \leq 6.0 m Ω/\Box at 12 μm fired film thickness

Viscosity

120 – 180 Kcps Brookfield HBT SC4 – 14 spindle, 6R utility cup at 10 rpm, 25 °C

% Solids

80.0 ± 1.0 %

Solderability

Sn62/Pb36/Ag2 at 230 °C, RMA flux 5 second dip \geq 95 %

Solder Leaching

Sn62/Pb36/Ag2 at 230 °C, RMA flux

10 second dip up to 3 x 10 sec dip

Adhesion

Sn62/Pb36/Ag2 at 230 °C, RMA flux 80 x 80 mil pads

Initial: ≥ 5.0 lbs

48 hours @ 150 °C: \geq 3.0 lbs (1 x 850 °C)

 \geq 4.0 lbs (5 x 850 °C)

1000 hours @ 150 °C: \geq 3.0 lbs (1 x 850 °C)

 \geq 4.0 lbs (5 x 850 °C)

Wire Bond Adhesion

10 mil Al wire, 99.999 % Al, Elongation > 5 %

5 x 850 °C firing

Initial: $\geq 400.0 \text{ g}$ 1000 hours @ 150 °C: $\geq 400.0 \text{ g}$

Heraeus Electronics

Heraeus Deutschland GmbH & Co. KG Heraeusstraße 12 – 14 63450 Hanau, Germany www.heraeus-electronics.com

Americas

Phone +1 610 825 6050 electronics.americas@heraeus.com

Asia Pacific

Phone +65 6571 7649 electronics.apac@heraeus.com

China

Phone +86 53 5815 9601 electronics.china@heraeus.com

Europe, Middle East and Africa

Phone +49 6181 35 4370 electronics.emea@heraeus.com